



IN RE APPLICATION OF Stewart *et al.*

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EXAMINER: TRAN, Thien F.

SERIAL NO.: 10/091,086

GROUP ART UNIT: 2811

FILED: March 5, 2002

ATTY. DOCKET NO.: US02022

FOR: Attachment Of Surface Mount Devices To Printed Circuit Boards Using A Thermoplastic Adhesive

DATE: June 24, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

RESPONSE TO RESTRICTION REQUIREMENT

Sir:

This is a response to the restriction requirement mailed May 26, 2004, for the above referenced application.

In the restriction requirement, the claims of the present application have been restricted as follows:

Group I	Claims 1-3 and 5-55 drawn to a semiconductor device, classified in class 257, subclass 686
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Group II Claims 4 and 56-92 drawn to a process for making semiconductor devices board, classified in class 438, subclass 22+.

The application is further restricted to the following species

Species 1 Embodiment of Figure 1 (claims 1-3)

Species 2 Embodiment of Figure 2 (claims 5-8)

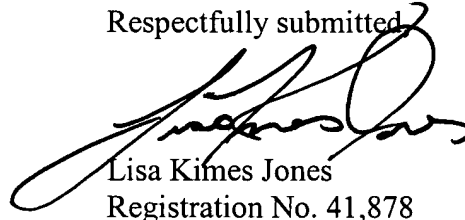
Species 3 Embodiment of Figure 3 (claims 9-55).

Applicants elect to prosecute the claims of Group I (Claims 1-3 and 5-55), species 3, with traverse.

It is respectfully submitted that the subject matter are interrelated such that a search of the multiple surface amount electronic device having the thermoplastic adhesive of Group I would require a search of the class and subclass of Group II. In order to facilitate prosecution, it is respectfully requested that all the claims be examined together.

If it would be of assistance, the Examiner is invited to contact the undersigned.

Respectfully submitted,



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Date: 6-24-2004

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